SCDS062B - JUNE 1998 - REVISED JUNE 2000

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Bus Hold on Data Inputs/Outputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

The SN74CBTH16211 provides 24 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as dual 12-bit bus switches with separate output-enable (\overline{OE}) inputs. It can be used as two 12-bit bus switches or one 24-bit bus switch. When \overline{OE} is low, the associated 12-bit bus switch is on, and the A port is connected to the B port. When \overline{OE} is high, the switch is open, and a high-impedance state exists between the two ports.

Active bus-hold circuitry is provided to hold unused or floating A and B ports at a valid logic level.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74CBTH16211 is characterized for operation from –40°C to 85°C.

DGG, DGV, OR DL PACKAGE (TOP VIEW)

			1
NC [1	56	10E
1A1 [2	55	20E
1A2	3	54] 1B1
1A3 [4	53] 1B2
1A4 [5	52] 1B3
1A5 [6	51] 1B4
1A6 [7	50] 1B5
GND [8	49	GND
1A7 🛚	9	48] 1B6
1A8 [10	47] 1B7
1A9 🛚	11	46] 1B8
1A10 [12] 1B9
1A11 [13] 1B10
1A12	14	43] 1B11
2A1	15	42] 1B12
2A2	16	41	2B1
V _{CC}	17	40	2B2
2A3 🛚	18	39	2B3
GND [19	38	GND
2A4 🛚	20	37	2B4
2A5	21	36	2B5
2A6	22	35	2B6
2A7	23	34	2B7
2A8	24		2B8
2A9	25	32	2B9
2A10	26	31	2B10
2A11	27	30	2B11
2A12	28	29	2B12

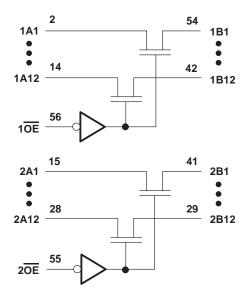
NC - No internal connection

FUNCTION TABLE (each bus switch)

INPUT OE	FUNCTION		
L	A port = B port		
n ₃ H	Disconnect		

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input voltage range, V _I (see Note 1)		0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_I < 0$)		–50 mA
Package thermal impedance, θ _{JA} (see Note 2):	: DGG package	64°C/W
	DGV package	48°C/W
	DL package	56°C/W
Storage temperature range, T _{stg}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4	5.5	V
VIH	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51.

SCDS062B - JUNE 1998 - REVISED JUNE 2000

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER		TEST CONDITION	ONS	MIN	TYP [†]	MAX	UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$				-1.2	V	
Ī.,	Control inputs	$V_{CC} = 0 V$,	V _I = 5.5 V				±10		
l _I	All inputs	V _{CC} = 5.5 V,	V _I = 5.5 V or GND				±10	μΑ	
I _{BHL} ‡		$V_{CC} = 4.5 \text{ V},$	V _I = 0.8 V		100			μΑ	
IBHH§		$V_{CC} = 4.5 \text{ V},$	V _I = 2 V		-100			μΑ	
IBHLO	1	V _{CC} = 5.5 V,	$V_{I} = 0 \text{ to } 5.5 \text{ V}$		500			μΑ	
Івнно) #	V _{CC} = 5.5 V,	V _I = 0 to 5.5 V		-500			μΑ	
Icc		$V_{CC} = 5.5 V,$	$I_{O} = 0$,	$V_I = V_{CC}$ or GND			3	μΑ	
ΔICC	Control inputs	$V_{CC} = 5.5 V,$	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA	
	$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$ $V_{CC} = 4.5 \text{ V}$		V _I = 2.4 V,	I _I = 15 mA		14	20		
r _{on} ≉			V _I = 0	I _I = 64 mA		5	7	Ω	
		V _{CC} = 4.5 V		I _I = 30 mA		5	7		
		V _I = 2.4 V,	I _I = 15 mA		8	12			

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN M	AX	MIN	MAX	
tpd□	A or B	B or A	0.	.35		0.25	ns
t _{en}	ŌĒ	A or B	,	9.9	1	9.6	ns
^t dis	ŌĒ	A or B	9	9.5	1	8.3	ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



[‡] The bus hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{II} max.

[§] The bus hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

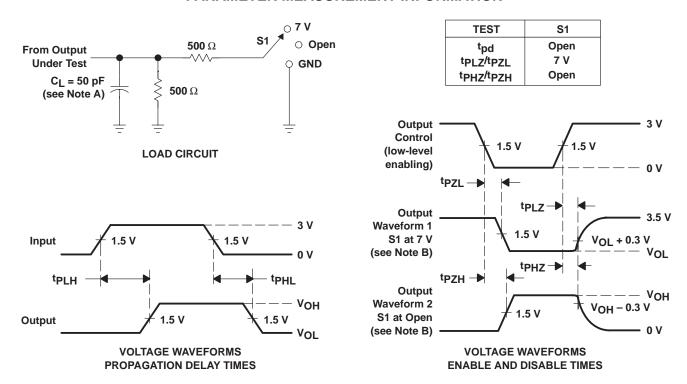
[¶] An external driver must source at least IBHLO to switch this node from low to high.

[#] An external driver must sink at least IBHHO to switch this node from high to low.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

^{*}Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \,\Omega_{1}$ t_r \leq 2.5 ns. t_r \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgment, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

Customers are responsible for their applications using TI components.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 2000, Texas Instruments Incorporated